



(43) International Publication Date
22 January 2015 (22.01.2015)

- (51) International Patent Classification:
H01L 23/28 (2006.01) *H01L 21/56* (2006.01)
- (21) International Application Number:
PCT/SG2014/000335
- (22) International Filing Date:
16 July 2014 (16.07.2014)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
201305439-0 16 July 2013 (16.07.2013) SG
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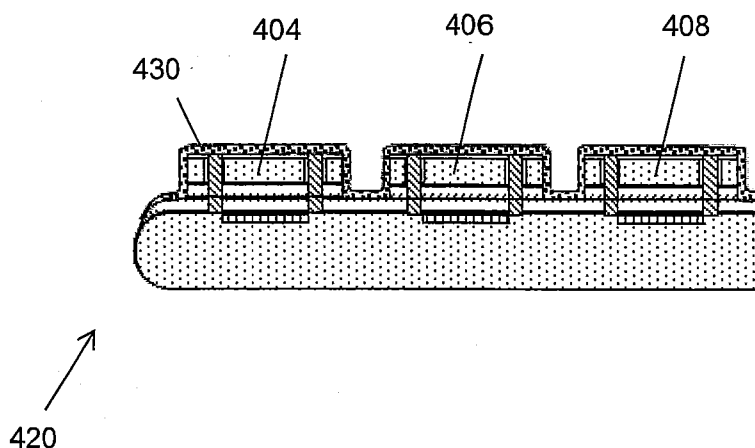
(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY,
BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IR, IS, JP, KE, KG, KN, KP, KR,
KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME,
MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ,
OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA,
SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM,
ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ,
UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ,
TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK,
EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV,
MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) Title: METHOD AND APPARATUS FOR CHIP-TO-WAFER INTEGRATION



(57) Abstract: An apparatus and a method for chip-to-wafer integration is provided. The apparatus includes a coating module, a bonding module and a cleaning module. The method includes the steps of placing at least one chip on a wafer to form an integrated product, forming a film on the integrated product, such that the integrated product is substantially fluid-tight, and exerting a predetermined positive pressure on the film during permanent bonding of the at least one chip to the wafer. The method further includes the step of removing the film from the integrated product after permanent bonding of the at least one chip to the wafer.

Figure 4C